

1. General description

Silicon Carbide MOSFET in a TO263-7L plastic package, designed for high frequency, high efficiency systems.



2. Features and benefits

- Kelvin source configuration
- Low specific on-resistance
- Optimized dynamic performance
- Robust gate design
- 0V turn-off V_{GS} for simple gate driving
- 100% UIS Tested
- Easy to parallel
- RoHS compliant

3. Applications

- Switching mode power supplies
- UPS & Energy storage system
- Battery formation instrument
- PV MPPT and inverters
- EV Chargers
- Welding machines
- Moter Drives

4. Quick reference data

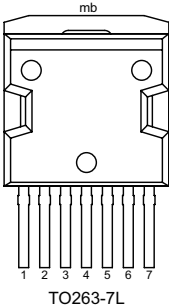
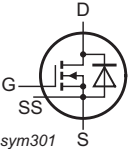
Table 1. Quick reference data

Table 17. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute maximum rating							
V _{DS}	drain-source voltage	25 °C ≤ T _j ≤ 175 °C		1700			V
I _D	drain current	V _{GS} = 18 V; T _{mb} = 25 °C		80			A
P _{tot}	total power dissipation	T _{mb} = 25 °C, T _j = 175 °C		536			W
T _j	junction temperature			-55 to 175			°C
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
R _{DS(on)}	drain-source on-state resistance	V _{GS} = 15 V; I _D = 50 A; T _j = 25 °C		-	35	-	mΩ
		V _{GS} = 18 V; I _D = 50 A; T _j = 25 °C		-	30	60	mΩ
Dynamic characteristics							
Q _{G(tot)}	total gate charge	I _D = 50 A; V _{DS} = 1200 V; V _{GS} = -4 V/18 V; T _j = 25 °C		-	176	-	nC
Q _{GD}	gate-drain charge			-	28	-	nC
Source-drain diode							
Q _r	recovered charge	I _{SD} = 50 A; V _{GS} = -4 V/18 V; di/dt = 3240 A/μs; R _g = 2.4 Ω; V _{DS} = 800 V; T _j = 25 °C		-	651	-	nC

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		
2	SS	source sense		
3-7	S	source		
mb	D	mounting base; connected to drain		

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WNSC2M35170B7	TO263-7L	WNSC2M35170B76J	Reel	800	TO263P-7L	05-Mar-2024

7. Marking

Table 4. Marking codes

Type number	Marking codes
WNSC2M35170B7	WNSC2M 35170B7

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{DS}	drain-source voltage	$25\text{ °C} \leq T_j \leq 175\text{ °C}$		1700	V
$V_{GS,max}$	gate-source voltage	Absolute maximum values		-12 to 24	V
$V_{GS,op}$	gate-source voltage	Recommended operational values		-4 to 18	V
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C}$; $T_j = 175\text{ °C}$		536	W
I_D	drain current	$V_{GS} = 18\text{ V}$; $T_{mb} = 25\text{ °C}$		80	A
		$V_{GS} = 18\text{ V}$; $T_{mb} = 100\text{ °C}$		57	A
I_{DM}	peak drain current	pulse width t_p limited by T_{jmax}	Fig.17	160	A
I_S	continuous diode current	$V_{GS} = -4\text{ V}$; $T_{mb} = 25\text{ °C}$		84	A
I_{SM}	pulse diode current	$V_{GS} = -4\text{ V}$; pulse width t_p limited by T_{jmax}		160	A
E_{as}	single pulse drain-to-source avalanche	$I_{AS} = 30\text{ A}$; $L = 1\text{ mH}$; $V_{DD} = 100\text{ V}$; $T_j = 25\text{ °C}$		450	mJ
T_{stg}	storage temperature			-55 to 175	°C
T_j	junction temperature			-55 to 175	°C
$T_{sld(M)}$	peak soldering temperature			260	°C

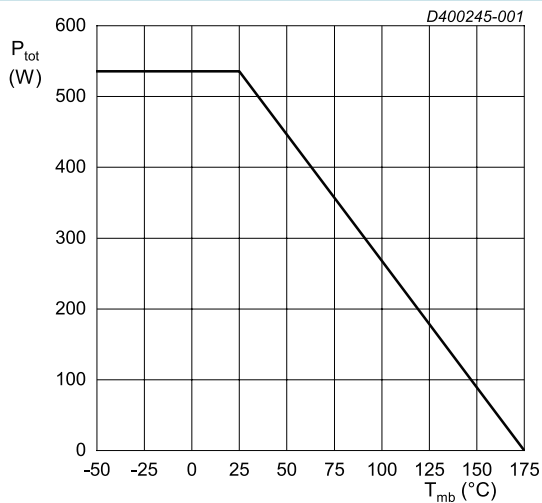


Fig. 1. Total power dissipation as a function of mounting base temperature; maximum values

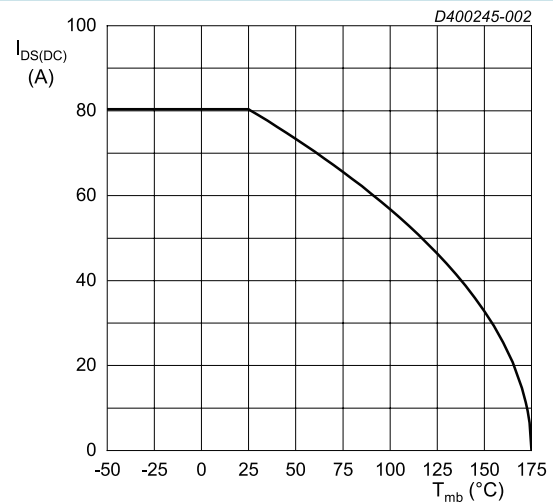


Fig. 2. Continuous Drain Current as a function of mounting base temperature

9. Thermal & Mechanical characteristics

Table 6. Thermal & Mechanical characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base			-	0.28	-	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air		-	40	-	K/W

Note: Device is ESD sensitive. Handling precautions are recommended.

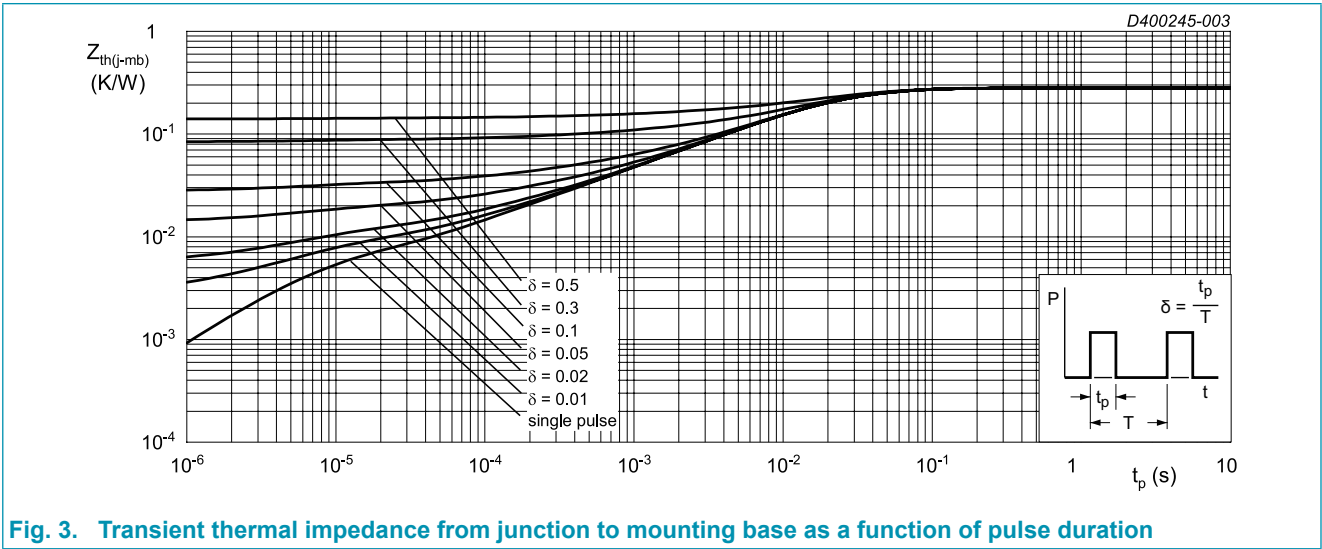
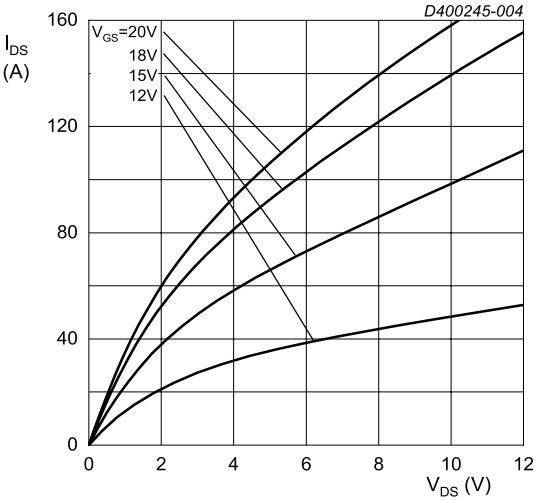


Fig. 3. Transient thermal impedance from junction to mounting base as a function of pulse duration

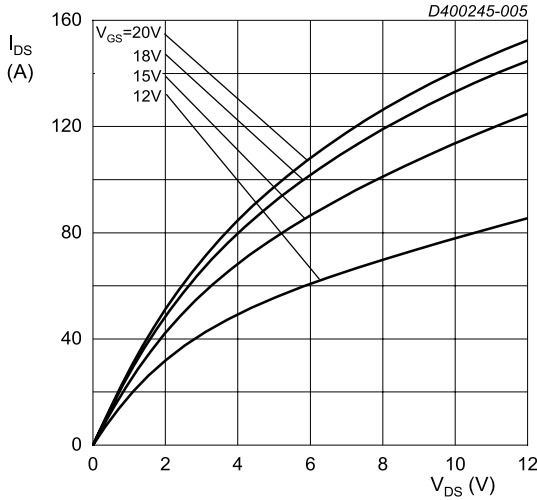
10. Characteristics

Table 7. Characteristics

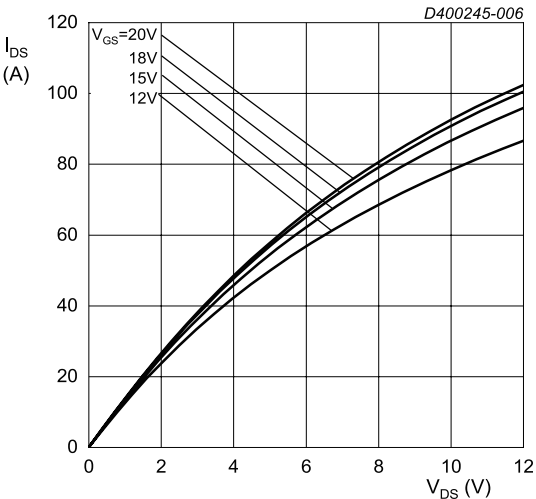
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 100 \mu A$; $V_{GS} = 0 V$; $T_J = 25^\circ C$		1700	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 20 mA$; $V_{DS} = 10 V$; $T_J = 25^\circ C$		1.9	2.6	3.5	V
		$I_D = 20 mA$; $V_{DS} = 10 V$; $T_J = 175^\circ C$		-	1.9	-	V
I_{DSS}	drain leakage current	$V_{DS} = 1700 V$; $V_{GS} = 0 V$; $T_J = 25^\circ C$		-	0.1	100	μA
		$V_{DS} = 1700 V$; $V_{GS} = 0 V$; $T_J = 175^\circ C$		-	1	-	μA
I_{GSS}	gate leakage current	$V_{GS} = 24 V$; $V_{DS} = 0 V$; $T_J = 25^\circ C$		-	10	100	nA
		$V_{GS} = -12 V$; $V_{DS} = 0 V$; $T_J = 25^\circ C$		-	10	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 15 V$; $I_D = 50 A$; $T_J = 25^\circ C$		-	35	-	m Ω
		$V_{GS} = 18 V$; $I_D = 50 A$; $T_J = 25^\circ C$		-	30	60	m Ω
		$V_{GS} = 18 V$; $I_D = 50 A$; $T_J = 175^\circ C$		-	66	-	m Ω
R_G	gate resistance	$f = 1 MHz$; $T_J = 25^\circ C$		-	0.73	-	Ω
g_{fs}	transconductance	$V_{DS} = 20 V$; $I_D = 50 A$; $T_J = 25^\circ C$		-	23	-	S
Dynamic characteristics							
$Q_{G(tot)}$	total gate charge	$I_D = 50 A$; $V_{DS} = 1200 V$; $V_{GS} = -4 V/18 V$; $T_J = 25^\circ C$		-	176	-	nC
Q_{GS}	gate-source charge			-	69	-	nC
Q_{GD}	gate-drain charge			-	28	-	nC
C_{iss}	input capacitance	$V_{DS} = 1700 V$; $V_{GS} = 0 V$; $f = 1 MHz$; $T_J = 25^\circ C$		-	3590	-	pF
C_{oss}	output capacitance			-	113	-	pF
C_{rss}	reverse transfer capacitance			-	11.6	-	pF
E_{oss}	Coss stored energy			-	56.5	-	μJ
$t_{d(on)}$	turn-on delay time	$V_{DS} = 800 V$; $V_{GS} = -4 V/18 V$; $R_{G(ext)} = 2.4 \Omega$; $I_D = 50 A$; $L = 100 \mu H$; $T_J = 25^\circ C$		-	15	-	ns
t_r	rise time			-	31	-	ns
$t_{d(off)}$	turn-off delay time			-	33	-	ns
t_f	fall time			-	12	-	ns
E_{on}	turn-on energy (Body Diode FWD)			-	384	-	μJ
E_{off}	turn-off energy (Body Diode FWD)			-	288	-	μJ
Source-drain diode							
V_{SD}	source-drain voltage	$V_{GS} = 0 V$; $I_{SD} = 25 A$; $T_J = 25^\circ C$		-	3.5	-	V
		$V_{GS} = -4 V$; $I_{SD} = 25 A$; $T_J = 25^\circ C$		-	5.0	-	V
		$V_{GS} = -4 V$; $I_{SD} = 25 A$; $T_J = 175^\circ C$		-	4.4	-	V
t_{rr}	reverse recovery time	$I_{SD} = 50 A$; $V_{GS} = -4 V/18 V$; $di/dt = 3240 A/\mu s$; $R_G = 2.4 \Omega$; $V_{DS} = 800 V$; $T_J = 25^\circ C$		-	24	-	ns
Q_r	recovered charge			-	651	-	nC
I_{rrm}	reverse recovery current			-	45	-	A



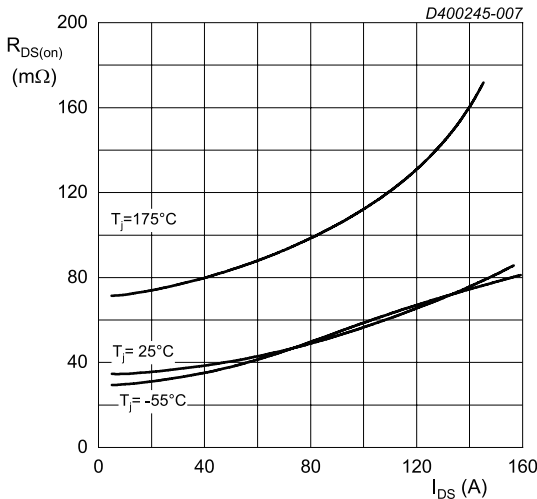
$T_j = -55\text{ }^{\circ}\text{C}$; $t_p < 200\text{ }\mu\text{s}$
Fig. 4. Output characteristics; drain current as a function of drain-source voltage; typical values



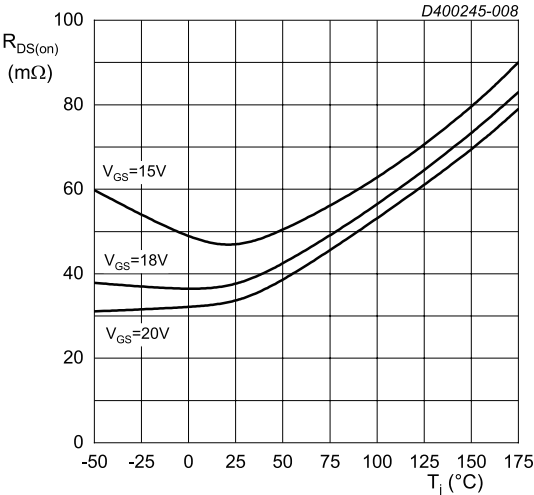
$T_j = 25\text{ }^{\circ}\text{C}$; $t_p < 200\text{ }\mu\text{s}$
Fig. 5. Output characteristics; drain current as a function of drain-source voltage; typical values



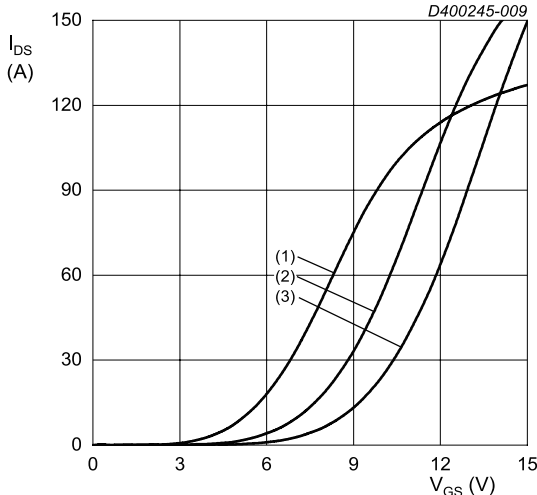
$T_j = 175\text{ }^{\circ}\text{C}$; $t_p < 200\text{ }\mu\text{s}$
Fig. 6. Output characteristics; drain current as a function of drain-source voltage; typical values



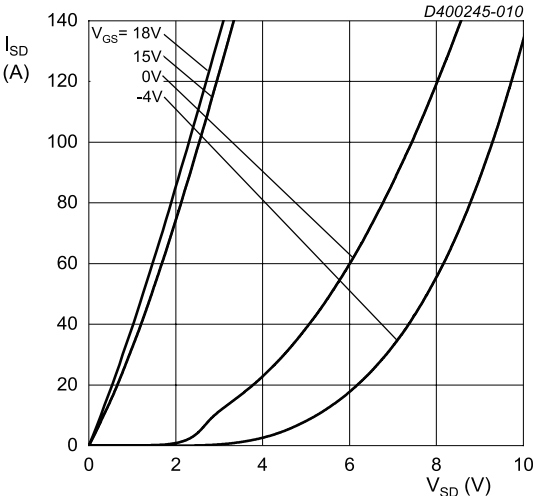
$V_{GS} = 18\text{ V}$; $t_p < 200\text{ }\mu\text{s}$
Fig. 7. Drain-source on-state resistance as a function of drain current; typical values



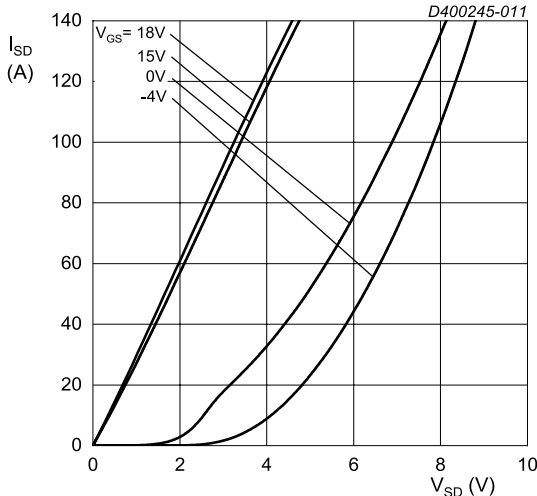
$I_{DS} = 50\text{ A}; t_p < 200\text{ }\mu\text{s}$
Fig. 8. Drain-source on-state resistance as a function of junction temperature



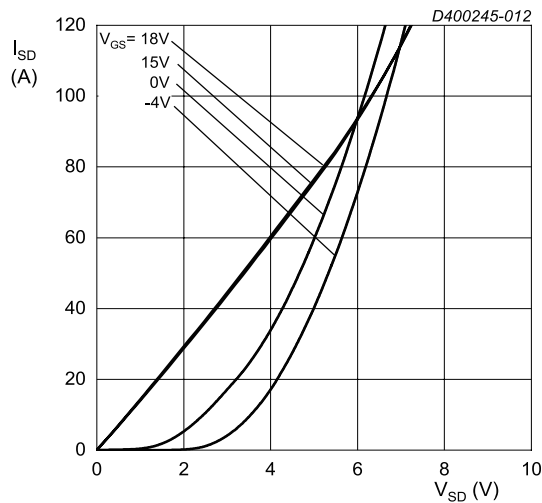
$V_{DS} = 20\text{ V}; t_p < 200\text{ }\mu\text{s}$
(1) $T_j = 175\text{ }^\circ\text{C}$
(2) $T_j = 25\text{ }^\circ\text{C}$
(3) $T_j = -55\text{ }^\circ\text{C}$
Fig. 9. Transfer characteristics; drain current as a function of gate-source voltage; typical values



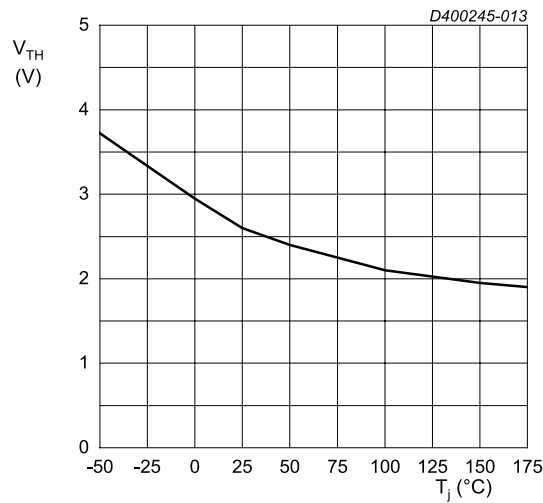
$T_j = -55\text{ }^\circ\text{C}; t_p < 200\text{ }\mu\text{s}$
Fig. 10. Body diode forward characteristics; typical values



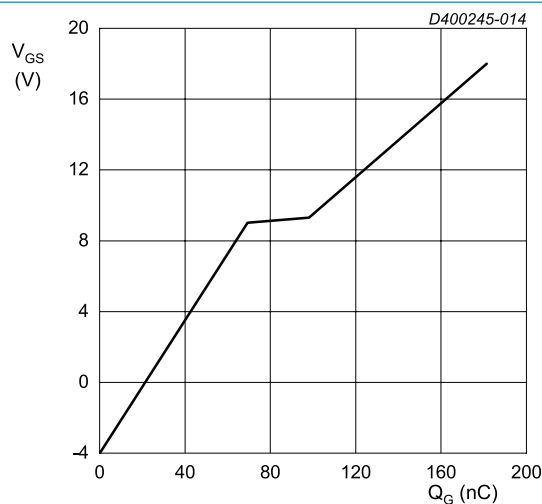
$T_j = 25\text{ }^\circ\text{C}; t_p < 200\text{ }\mu\text{s}$
Fig. 11. Body diode forward characteristics; typical values



$T_j = 175\text{ }^{\circ}\text{C}; t_p < 200\text{ }\mu\text{s}$
Fig. 12. Body diode forward characteristics; typical values



$V_{DS} = 10\text{ V}; I_{DS} = 20\text{ mA}$
Fig. 13. Threshold voltage as a function of junction temperature



$I_{DS} = 50\text{ A}; I_{GS} = 0.1\text{ mA}; V_{DS} = 1200\text{ V}; T_j = 25\text{ }^{\circ}\text{C}$
Fig. 14. Gate-source voltage as a function of gate charge; typical values

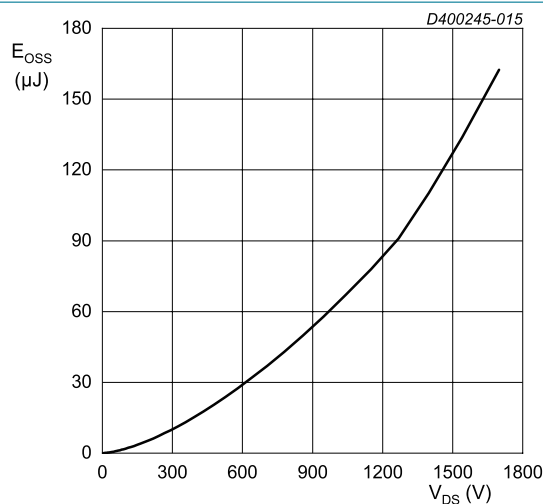
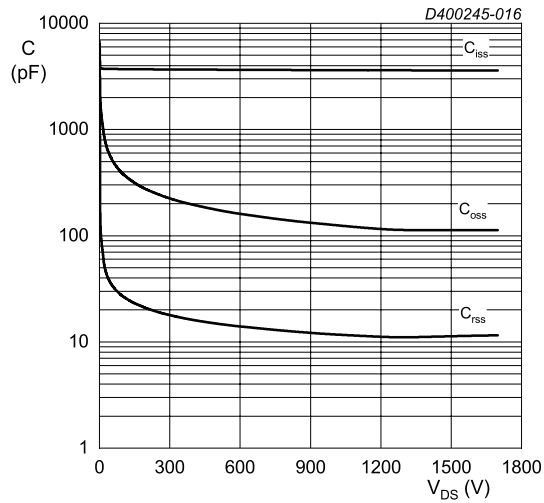
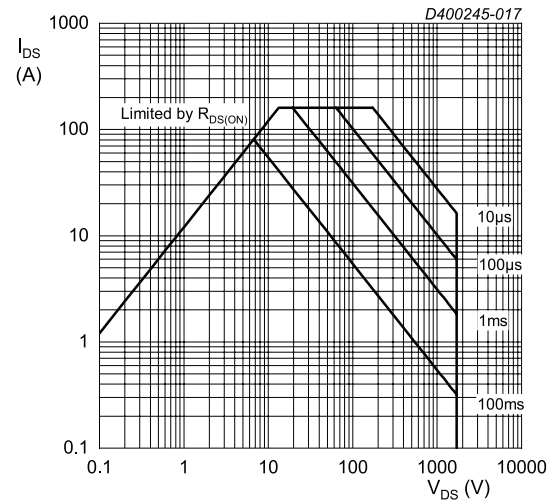


Fig. 15. Output capacitor stored energy as a function of drain-source voltage



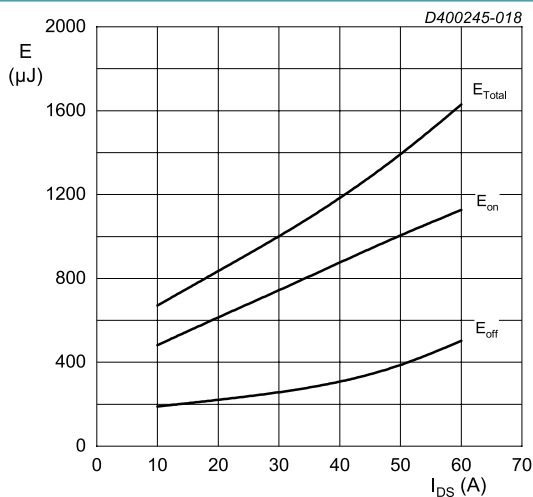
$V_{DS} = 0 - 1700$ V
 $T_j = 25$ °C; $V_{AC} = 25$ mV; $f = 1$ MHz

Fig. 16. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



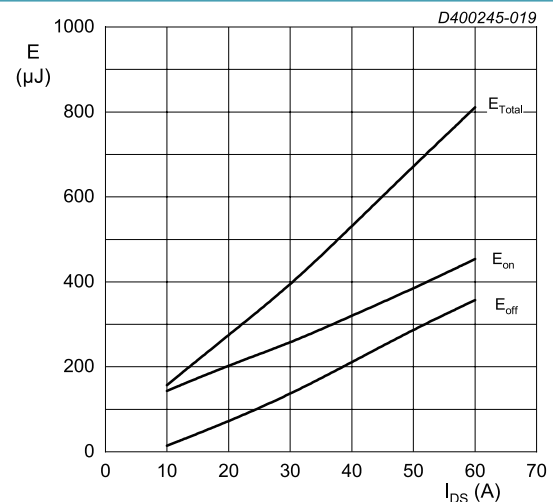
$T_j = 25$ °C; $D = 0$
 Parameter: t_p

Fig. 17. Forward bias safe operating area



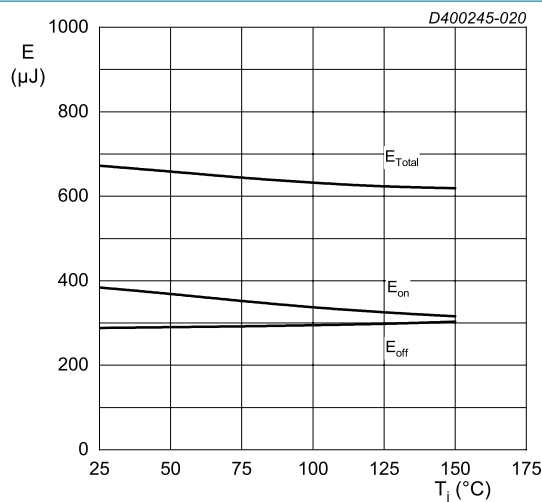
$T_j = 25$ °C; $V_{DD} = 1200$ V; $R_{G(ext)} = 2.4$ Ω;
 $V_{GS} = -4$ V/18 V; $L = 100$ µH
 FWD = WNSC2M35170B7

Fig. 18. Clamped Inductive Switching Energy as a function of drain current



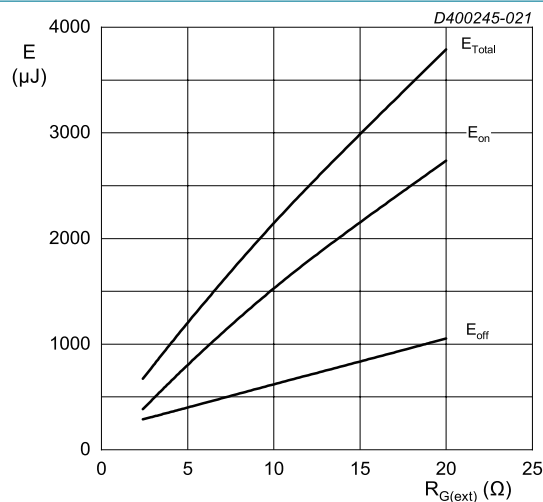
$T_j = 25$ °C; $V_{DD} = 800$ V; $R_{G(ext)} = 2.4$ Ω;
 $V_{GS} = -4$ V/18 V; $L = 100$ µH
 FWD = WNSC2M35170B7

Fig. 19. Clamped Inductive Switching Energy as a function of drain current



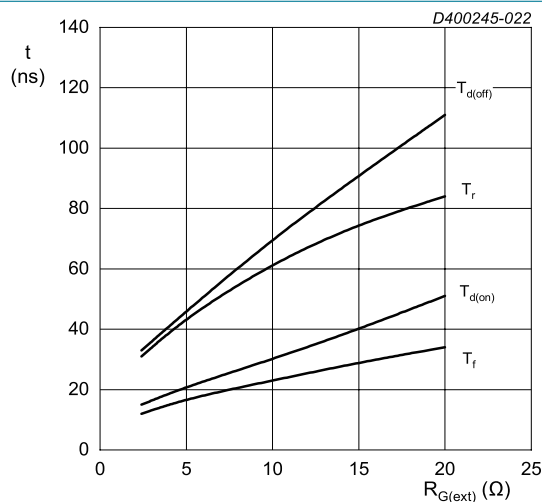
$I_{\text{DS}} = 50 \text{ A}$; $V_{\text{DD}} = 800 \text{ V}$; $R_{\text{G(ext)}} = 2.4 \Omega$;
 $V_{\text{GS}} = -4 \text{ V}/18 \text{ V}$; $L = 100 \mu\text{H}$
FWD = WNSC2M35170B7

Fig. 20. Clamped Inductive Switching Energy as a function of junction temperature



$T_j = 25 \text{ }^{\circ}\text{C}$; $V_{\text{DD}} = 800 \text{ V}$; $I_{\text{DS}} = 50 \text{ A}$; $V_{\text{GS}} = -4 \text{ V}/18 \text{ V}$
FWD = WNSC2M35170B7; $L = 100 \mu\text{H}$

Fig. 21. Clamped Inductive Switching Energy as a function of external gate resistance



$T_j = 25 \text{ }^{\circ}\text{C}$; $V_{\text{DD}} = 800 \text{ V}$; $I_{\text{DS}} = 50 \text{ A}$; $V_{\text{GS}} = -4 \text{ V}/18 \text{ V}$
FWD = WNSC2M35170B7; $L = 100 \mu\text{H}$

Fig. 22. Switching time as a function of external gate resistance

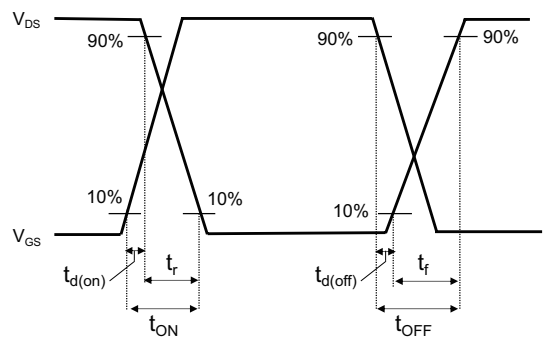
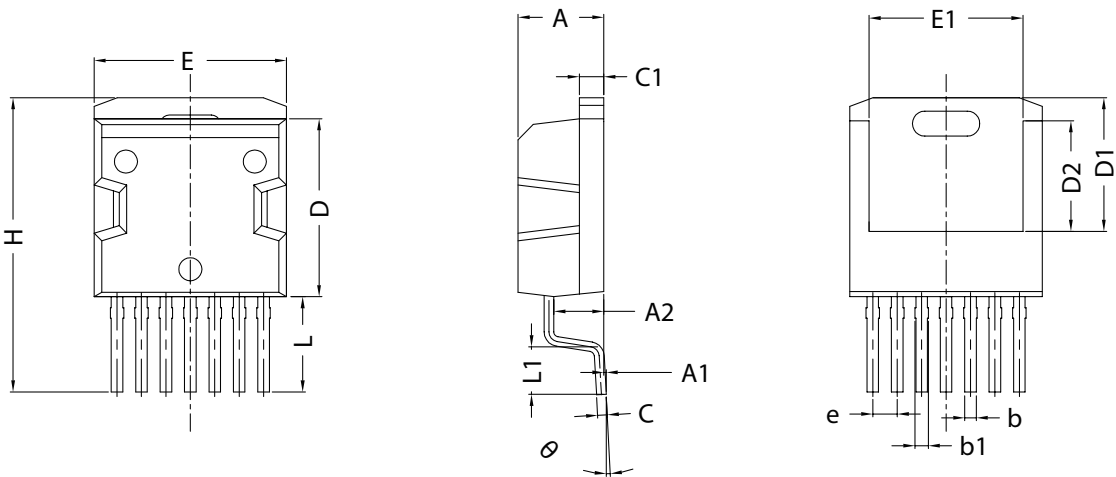


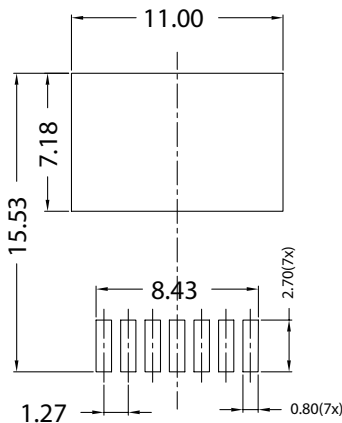
Fig. 23. Switching time definition

11. Package outline



Dim	All Dimensions in Millimeters		
	Min	Typ	Max
A	4.30	4.46	4.60
A1	0	0.13	0.25
A2	2.50	2.60	2.70
b	0.50	0.60	0.70
b1	0.50	0.70	0.90
C	0.40	0.52	0.60
C1	1.17	1.29	1.40
D	9.00	9.25	9.50
D1	6.80	6.95	7.10
D2	5.60	5.75	5.90
E	9.80	10.00	10.20
E1	7.90	8.00	8.10
e	1.27 BSC		
H	14.60	15.30	16.00
L	4.50	4.95	5.40
L1	2.10	2.47	2.80
θ	0°	4°	8°

Footprint :



12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.ween-semi.com>.

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Date of release: 25 June 2025